



Corres. and Mail  
**BOX AF**

#21 / *Amate*  
11.6.02  
*C. Moore*  
AMENDMENT UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
GROUP 2814  
PATENT APPLICATION

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q58486

Kouki OGAWA, et al.

Appln. No.: 09/538,469

Group Art Unit: 2814

Confirmation No.: 6688

Examiner: Nathan W. Ha

Filed: March 29, 2000

For: CAPACITOR-BUILT-IN TYPE PRINTED WIRING SUBSTRATE, PRINTED  
WIRING SUBSTRATE, AND CAPACITOR

**AMENDMENT UNDER 37 C.F.R. § 1.116**

*Don't enter 11/16/02*  
ATTN: **BOX AF**  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

Responsive to the outstanding final Office Action dated August 20, 2002, please amend  
the above-identified application as follows.

**IN THE CLAIMS:**

**Please enter the following amended claims:**

- 52  
506  
41*
1. (Four times amended) A printed wiring substrate having a planar surface and a built-in capacitor on which an IC chip is mounted, said printed wiring substrate comprising a capacitor accommodation cavity selected from the group consisting of a closed-bottom cavity and a through hole cavity extending in the thickness direction of the printed wiring substrate and a capacitor disposed in said cavity, characterized in that: